



Material Content Data Sheet



Sales Product Name		AIDK10S65C5		Issued		4. July 2019		
MA#		MA001891240						
Package		PG-TO263-2-1		Weight*		1466.50 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	siliconcarbide	409-21-2	0.800	0.05	0.05	545	545
leadframe	inorganic material	phosphorus	7723-14-0	0.225	0.02		154	
	non noble metal	iron	7439-89-6	0.751	0.05		512	
	non noble metal	copper	7440-50-8	749.949	51.14	51.21	511387	512053
	non noble metal	aluminium	7429-90-5	1.259	0.09	0.09	859	859
wire	non noble metal	aluminium	7429-90-5	1.259	0.09	0.09	859	859
encapsulation	organic material	carbon black	1333-86-4	8.349	0.57		5693	
	plastics	epoxy resin	-	91.844	6.26		62628	
	inorganic material	silicondioxide	60676-86-0	456.436	31.12	37.95	311241	379562
leadfinish	non noble metal	tin	7440-31-5	11.700	0.80	0.80	7978	7978
plating	inorganic material	phosphorus	7723-14-0	0.007	0.00		5	
	non noble metal	nickel	7440-02-0	2.778	0.19	0.19	1894	1899
solder	non noble metal	tin	7440-31-5	0.014	0.00		10	
	noble metal	silver	7440-22-4	0.018	0.00		12	
	non noble metal	lead	7439-92-1	0.689	0.05	0.05	470	492
heatspreader	inorganic material	phosphorus	7723-14-0	0.043	0.00		29	
	non noble metal	iron	7439-89-6	0.142	0.01		97	
	non noble metal	copper	7440-50-8	141.498	9.65	9.66	96486	96612
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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